

LB11961

Recommended Operating Conditions at Ta = 25°C (Note3)

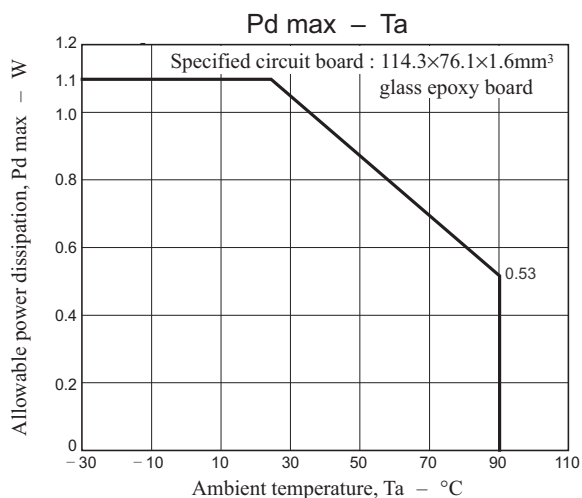
Parameter	Symbol	Conditions	Ratings	Unit
V _{CC} supply voltage	V _{CC}		4.5 to 16	V
V _{TH} input level voltage range	V _{TH}		0 to 9	V
Hall sensor input common-mode input voltage range	V _{ICM}		0.2 to 3	V

3. Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Electrical Characteristics Unless otherwise specified Ta = 25°C, V_{CC} = 12V (Note4)

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Circuit current	I _{CC1}	Drive mode	12	18	24	mA
	I _{CC2}	Lock protection mode	8	11	16	mA
6VREG voltage	V _{6VREG}	I _{6VREG} = 5mA	5.8	6	6.2	V
HB voltage	V _{HB}	I _{HB} = 5mA	1.10	1.25	1.40	V
CPWM high-level voltage	V _{CRH}		3.45	3.6	3.75	V
CPWM low-level voltage	V _{CRL}		1.95	2.05	2.15	V
CPWM oscillator frequency	FPWM	C = 100pF	18	25	32	kHz
CT pin high-level voltage	V _{CTH}		3.45	3.6	3.75	V
CT pin low-level voltage	V _{CTL}		1.55	1.7	1.85	V
ICT charge current	I _{CT1}		1.5	2	2.5	μA
ICT discharge current	I _{CT2}		0.15	0.2	0.25	μA
ICT charge/discharge current ratio	R _{CT}		8.5	10	11.5	
OUT output low saturation voltage	V _{OL}	I _O = 200mA		0.2	0.3	V
OUT output high saturation voltage	V _{OH}	I _O = 200mA		0.9	1.1	V
Hall sensor input sensitivity	V _{HN}	Zero peak value (including offset and hysteresis)		10	20	mV
RD/FG output pin low-level voltage	VR _{DL} /F _{GL}	I _{RD} /F _G = 5mA		0.2	0.3	V
RD/FG output pin leakage current	I _{RDL} /F _{GL}	VR _D /F _G = 7V			30	μA

4. Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



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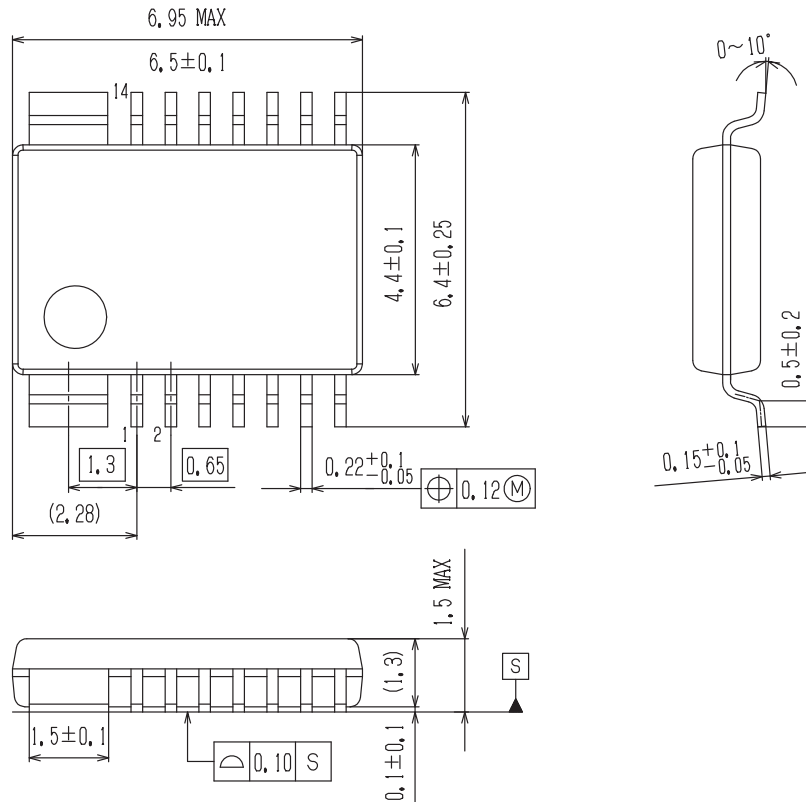
Package Dimensions

unit : mm

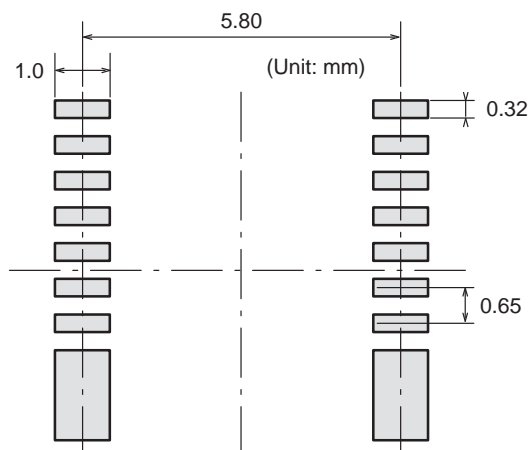
HSSOP14 (225mil)

CASE 944AA

ISSUE A



SOLDERING FOOTPRINT*



NOTES: 1. The measurements are not to guarantee but for reference only.
2. Land pattern design in Fin area to be altered in response to customer's individual application.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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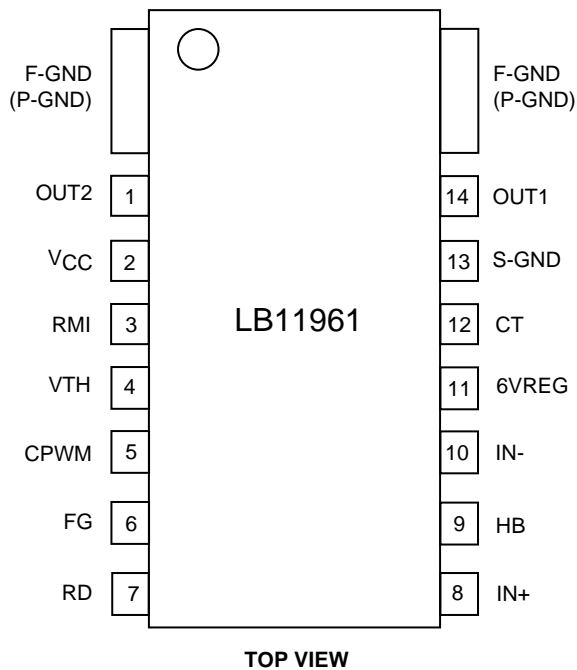
Truth Table

VTH	IN-	IN+	CPWM	CT	OUT1	OUT2	FG	RD	Mode
Low (open)	High	Low	High	Low	High	Low	Low	On	During rotation – drive (PWM off)
	Low	High			Low	High	Off		
High	High	Low	Low		Off	Low	Low		During rotation – regeneration (PWM on)
	Low	High			Low	Off	Off		
-	High	Low	-	High	High	Off	Low	Off	Lock protection
-	Low	High			Off	High	Off		

CPWM – High is the state where CPWM > VTH, and CPWM– Low is the state where CPWM < VTH.

Open : The LB11961 operates in full-speed mode when the thermistor is removed.

Pin Assignment

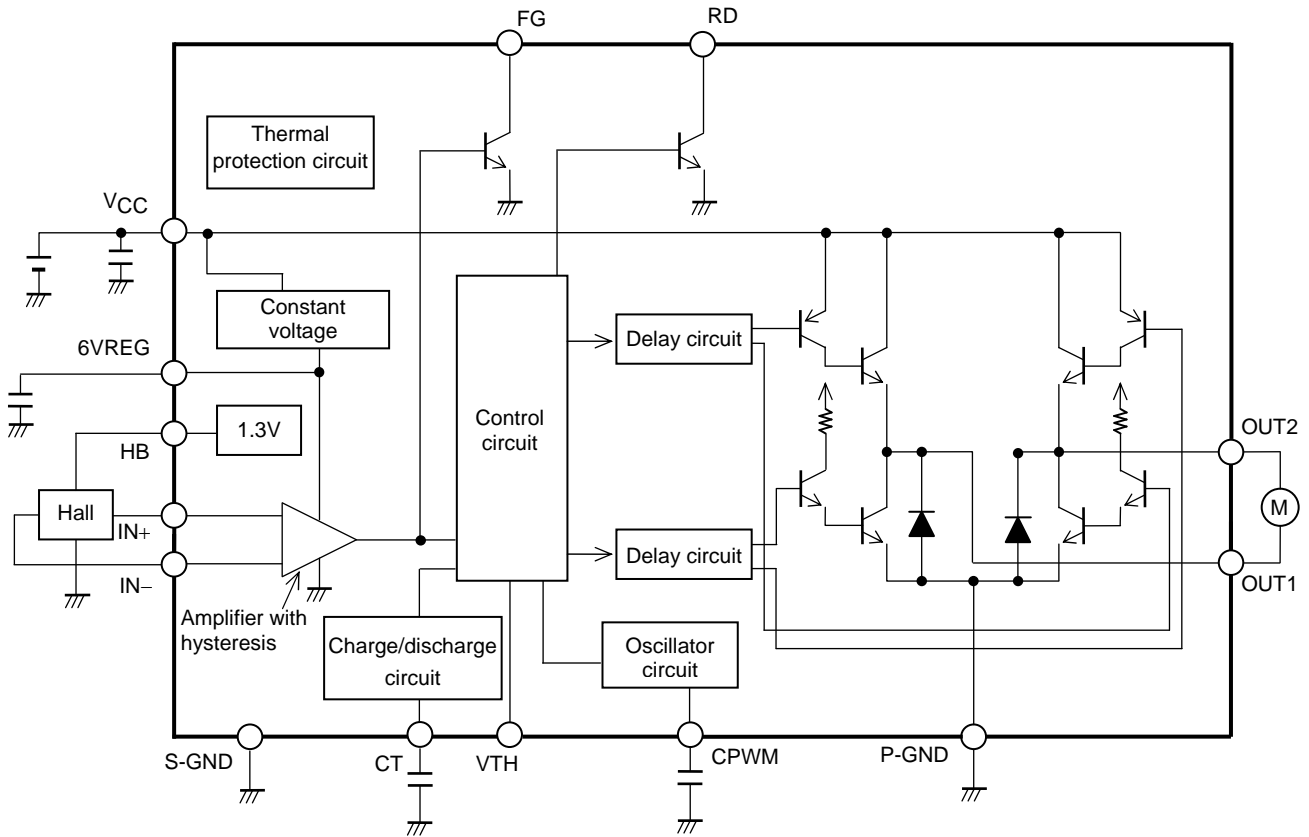


F-GND (P-GND) : The motor system ground and the heat sink. Since the heat generated by the chip is dissipated through F-GND, the thermal resistance is lowered by increasing the area of the copper foil and solder surface in the printed circuit pattern.

S-GND : Control system ground

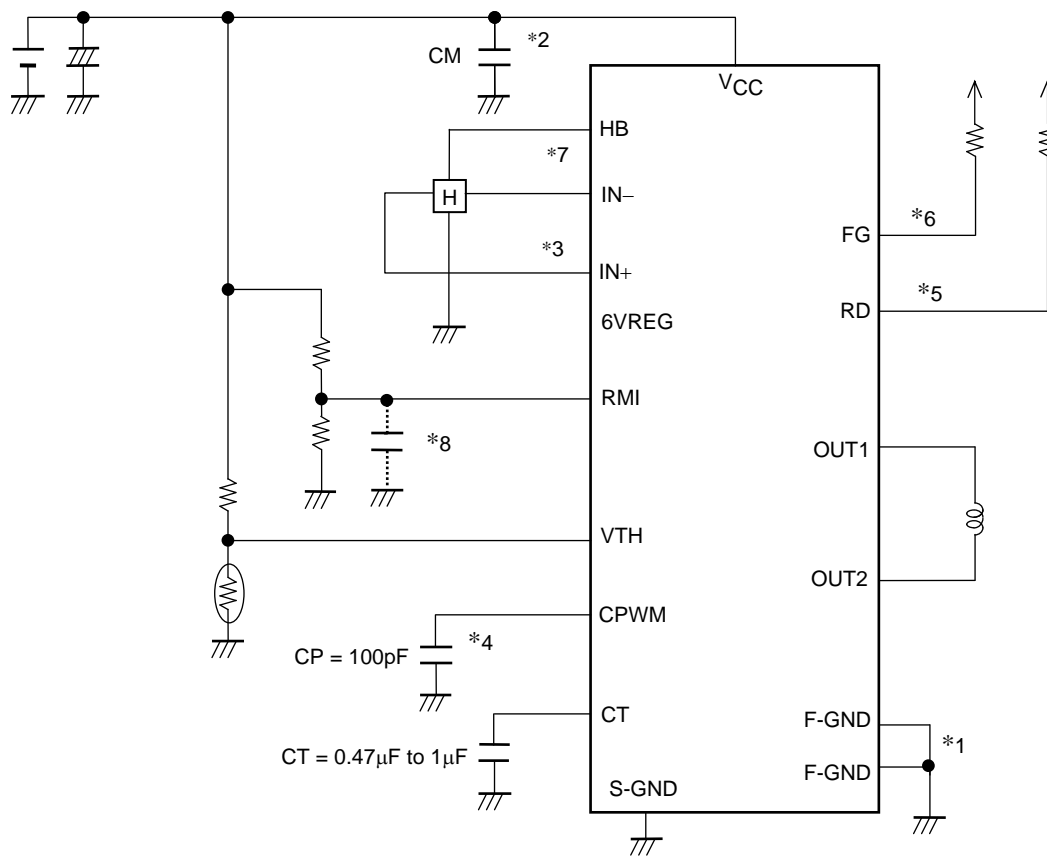
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Block Diagram



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Application Circuit Example



*1. Power supply and ground lines

P-GND is connected to the motor power supply system and S-GND is connected to the control circuit power supply system.

These two systems should be formed from separate lines and the control system external components should be connected to S-GND.

*2. Regeneration power supply stabilization capacitor

The capacitor CM provides power supply stabilization for both PWM drive and kickback absorption. A capacitor with a value of over $0.1\mu\text{F}$ is used for CM. A large capacitor must be used when the coil inductance is large or when the coil resistance is low. Since this IC adopts a technique in which switching is performed by the high side transistor and regeneration is handled by the low side transistor, the pattern connecting CM to VM and P-GND must be as wide and as short as possible.

*3. Hall sensor input

Lines that are as short as possible must be used to prevent noise from entering the system. The Hall sensor input circuit consists of a comparator with hysteresis (20mV). We recommend that the Hall sensor input level be at least three times this hysteresis, i.e. at least 60mVp-p.

*4. PWM oscillator frequency setting capacitor

If a value of 100pF is used for CP, the oscillator frequency will be $f = 25\text{kHz}$, and this will be the basic frequency of the PWM signal.

***5. RD output**

This is an open collector output. It outputs a low level when the motor is turning and a high level when it is stopped. This pin must be left open if unused.

*6. FG output

This is an open collector output, and a rotation count detection function can be implemented using this FG output, which corresponds to the phase switching. This pin must be left open if unused.

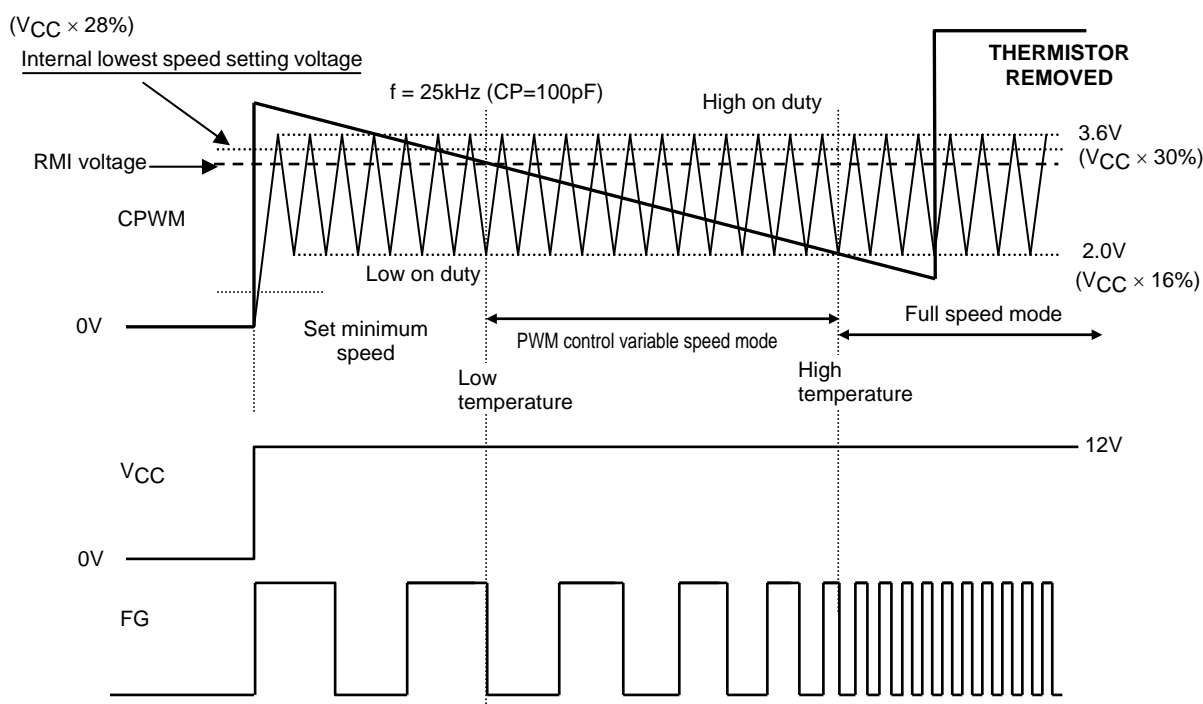
*7. HB pin

This pin provides a Hall effect sensor bias constant-voltage output of 1.25V.

*8. RMI pin

Connect this pin to VTH if unused. Even if unused, the IC is set internally to operate at a 10% drive duty at the voltage corresponding to the lowest speed. (The capacitor is used to set up full-speed mode at startup.)

Control Timing Chart



1. Set minimum speed mode

A VTH voltage level is generated when the thermistor detects the set temperature. At low temperatures, the fan motor turns at the lowest speed, which is set with the RMI pin. The LB11961 compares the CPWM oscillator voltage with the RMI pin voltage and sets the duty for the lowest drive state.

2. High speed ↔ low speed mode

The PWM signal is controlled by comparing the CPWM oscillation voltage that cycles between 1.2V and 3.8V and the VTH voltage.

When the VTH voltage is lower, the high and low side transistors are turned on, and when the VTH voltage is higher, the high side transistor is turned off and the coil current is regenerated through the low side transistor. Thus the output on duty increases as the VTH voltage becomes lower, the coil current increases, and the motor speed increases.

Rotation speed feedback is provided by the FG output.

3. Full-speed mode

The LB11961 switches to full-speed mode above a certain temperature.

4. Thermistor removed mode

If the thermistor is removed, the VTH input voltage will rise. However, the output will go to full drive at 100% and the motor will run at full speed.

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ORDERING INFORMATION

Device	Package	Wire Bond	Shipping(Qty/Packing)
LB11961-MPB-H	HSSOP14(225mil) (Pb-Free / Halogen Free)	Au-wire	70 / Fan-fold
LB11961-TLM-H	HSSOP14(225mil) (Pb-Free / Halogen Free)	Au-wire	2000 / Tape & Reel
LB11961-W-AH	HSSOP14(225mil) (Pb-Free / Halogen Free)	Cu-wire	2000 / Tape & Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

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